

Material Composition Declaration Sheet <MCD>**MICROCHIP**MCHP Package Code : **AWC**Package Type : **80 MQFP 14x14x2.0mm Matte Tin**

Material Name	Material Type/Grade	Material Weight (mg)	Material Percentage (%)	Chemical Ingredient	CAS No.	% Chemical in Material	% Chemical in Product	Chemical Mass in Product (mg)	PPM
Die	Silicon Die	45.00	4.55	Silicon	7440-21-3	95.0000	4.3267	42.7500	43267
				Various	Various	5.0000	0.2277	2.2500	2277
Mold Compound	Epoxy	675.00	68.32	Epoxy Resins	25928-94-3	15.0000	10.2475	101.2500	102475
				Silica	60676-86-0	85.0000	58.0690	573.7500	580690
Die Attach	Epoxy	7.45	0.75	Epoxy Resins	25928-94-3	22.0000	0.1659	1.6390	1659
				Silver	7440-222-4	78.0000	0.5881	5.8110	5881
IC frame	Copper Alloy	228.50	23.13	Copper	7440-50-8	96.2000	22.2476	219.8170	222476
				Silicon	7440-21-3	0.6500	0.1503	1.48525	1503
				Magnesium	7439-95-4	0.1500	0.0347	0.34275	347
				Nickel	7440-02-0	3.0000	0.6938	6.8550	6938
Leadframe	Metal	3.00	0.30	Silver	7440-22-4	100.0000	0.3036	3.0000	3036
Solderplate	Sn	14.40	1.46	Tin	7440-31-5	100.0000	1.4574	14.4000	14574
Bonding Wire	Gold	14.70	1.49	Gold	7440-57-5	100.0000	1.4876	14.6980	14876
Total (PKG Weight, mg)		988.05	100.00				100.00	988.05	1000000

This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) without exemption (zero)

Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.

If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.

Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL IQTM family of databases to obtain a test report at <http://iq.ul.com/plastics/>

The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.

Microchip Technology Incorporated believes the information in this form concerning substances restricted by RoHS in Microchip Technology Incorporated's semiconductor devices in their original packing materials is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the completeness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. Supplier information is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. Information is provided only as estimates of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not include trace levels of dopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts.

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